

LM324, LM324A, LM324E, LM224, LM2902, LM2902E, LM2902V, NCV2902

MAXIMUM RATINGS (T_A = +25°C, unless otherwise noted.)

Rating	Symbol	Value	Unit
Power Supply Voltages Single Supply Split Supplies	V _{CC} V _{CC} , V _{EE}	32 ±16	V _{dc}
Input Differential Voltage Range (Note 1)	V _{IDR}	±32	V _{dc}
Input Common Mode Voltage Range	V _{ICR}	–0.3 to 32	V _{dc}
Output Short Circuit Duration	t _{SC}	Continuous	
Junction Temperature	T _J	150	°C
Thermal Resistance, Junction–to–Air (Note 2) Case 646 Case 751A Case 948G	R _{θJA}	118 156 190	°C/W
Storage Temperature Range	T _{stg}	–65 to +150	°C
Operating Ambient Temperature Range LM224 LM324, LM324A, LM324E LM2902, LM2902E LM2902V, NCV2902 (Note 3)	T _A	–25 to +85 0 to +70 –40 to +105 –40 to +125	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Split Power Supplies.
2. All R_{θJA} measurements made on evaluation board with 1 oz. copper traces of minimum pad size. All device outputs were active.
3. NCV2902 is qualified for automotive use.

ESD RATINGS

Rating	HBM	MM	Unit
ESD Protection at any Pin (Human Body Model – HBM, Machine Model – MM) NCV2902 (Note 3)	2000	200	V
LM324E, LM2902E	2000	200	V
LM324DG/DR2G, LM2902DG/DR2G	200	100	V
All Other Devices	2000	200	V

LM324, LM324A, LM324E, LM224, LM2902, LM2902E, LM2902V, NCV2902

ELECTRICAL CHARACTERISTICS ($V_{CC} = 5.0\text{ V}$, $V_{EE} = \text{GND}$, $T_A = 25^\circ\text{C}$, unless otherwise noted.)

Characteristics	Symbol	LM224			LM324A			LM324, LM324E			LM2902, LM2902E			LM2902V/NCV2902			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage $V_{CC} = 5.0\text{ V}$ to 30 V $V_{ICR} = 0\text{ V}$ to $V_{CC} - 1.7\text{ V}$, $V_O = 1.4\text{ V}$, $R_S = 0\ \Omega$ $T_A = 25^\circ\text{C}$ $T_A = T_{\text{high}}$ (Note 4) $T_A = T_{\text{low}}$ (Note 4)	V_{IO}	–	2.0	5.0	–	2.0	3.0	–	2.0	7.0	–	2.0	7.0	–	2.0	7.0	mV
Average Temperature Coefficient of Input Offset Voltage $T_A = T_{\text{high}}$ to T_{low} (Notes 4 and 6)	$\Delta V_{IO}/\Delta T$	–	7.0	–	–	7.0	30	–	7.0	–	–	7.0	–	–	7.0	–	$\mu\text{V}/^\circ\text{C}$
Input Offset Current $T_A = T_{\text{high}}$ to T_{low} (Note 4)	I_{IO}	–	3.0	30	–	5.0	30	–	5.0	50	–	5.0	50	–	5.0	50	nA
Average Temperature Coefficient of Input Offset Current $T_A = T_{\text{high}}$ to T_{low} (Notes 4 and 6)	$\Delta I_{IO}/\Delta T$	–	10	–	–	10	300	–	10	–	–	10	–	–	10	–	$\text{pA}/^\circ\text{C}$
Input Bias Current $T_A = T_{\text{high}}$ to T_{low} (Note 4)	I_{IB}	–	–90	–150	–	–45	–100	–	–90	–250	–	–90	–250	–	–90	–250	nA
Input Common Mode Voltage Range (Note 5) $V_{CC} = 30\text{ V}$ $T_A = +25^\circ\text{C}$ $T_A = T_{\text{high}}$ to T_{low} (Note 4)	V_{ICR}	0	–	28.3	0	–	28.3	0	–	28.3	0	–	28.3	0	–	28.3	V
Differential Input Voltage Range	V_{IDR}	–	–	V_{CC}	–	–	V_{CC}	–	–	V_{CC}	–	–	V_{CC}	–	–	V_{CC}	V
Large Signal Open Loop Voltage Gain $R_L = 2.0\text{ k}\Omega$, $V_{CC} = 15\text{ V}$, for Large V_O Swing $T_A = T_{\text{high}}$ to T_{low} (Note 4)	A_{VOL}	50	100	–	25	100	–	25	100	–	25	100	–	25	100	–	V/mV
Channel Separation $10\text{ kHz} \leq f \leq 20\text{ kHz}$, Input Referenced	CS	–	–120	–	–	–120	–	–	–120	–	–	–120	–	–	–120	–	dB
Common Mode Rejection, $R_S \leq 10\text{ k}\Omega$	CMR	70	85	–	65	70	–	65	70	–	50	70	–	50	70	–	dB
Power Supply Rejection	PSR	65	100	–	65	100	–	65	100	–	50	100	–	50	100	–	dB

4. LM224: $T_{\text{low}} = -25^\circ\text{C}$, $T_{\text{high}} = +85^\circ\text{C}$
 LM324/LM324A/LM324E: $T_{\text{low}} = 0^\circ\text{C}$, $T_{\text{high}} = +70^\circ\text{C}$
 LM2902/LM2902E: $T_{\text{low}} = -40^\circ\text{C}$, $T_{\text{high}} = +105^\circ\text{C}$
 LM2902V & NCV2902: $T_{\text{low}} = -40^\circ\text{C}$, $T_{\text{high}} = +125^\circ\text{C}$
NCV2902 is qualified for automotive use.

5. The input common mode voltage or either input signal voltage should not be allowed to go negative by more than 0.3 V . The upper end of the common mode voltage range is $V_{CC} - 1.7\text{ V}$, but either or both inputs can go to $+32\text{ V}$ without damage, independent of the magnitude of V_{CC} .
6. Guaranteed by design.

LM324, LM324A, LM324E, LM224, LM2902, LM2902E, LM2902V, NCV2902

ELECTRICAL CHARACTERISTICS ($V_{CC} = 5.0\text{ V}$, $V_{EE} = \text{GND}$, $T_A = 25^\circ\text{C}$, unless otherwise noted.)

Characteristics	Symbol	LM224			LM324A			LM324, LM324E			LM2902, LM2902E			LM2902V/NCV2902			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Output Voltage – High Limit $V_{CC} = 5.0\text{ V}$, $R_L = 2.0\text{ k}\Omega$, $T_A = 25^\circ\text{C}$ $V_{CC} = 30\text{ V}$ $R_L = 2.0\text{ k}\Omega$ ($T_A = T_{\text{high}}$ to T_{low}) (Note 7) $V_{CC} = 30\text{ V}$ $R_L = 10\text{ k}\Omega$ ($T_A = T_{\text{high}}$ to T_{low}) (Note 7)	V_{OH}	3.3	3.5	–	3.3	3.5	–	3.3	3.5	–	3.3	3.5	–	3.3	3.5	–	V
Output Voltage – Low Limit, $V_{CC} = 5.0\text{ V}$, $R_L = 10\text{ k}\Omega$, $T_A = T_{\text{high}}$ to T_{low} (Note 7)	V_{OL}	–	5.0	20	–	5.0	20	–	5.0	20	–	5.0	100	–	5.0	100	mV
Output Source Current ($V_{ID} = +1.0\text{ V}$, $V_{CC} = 15\text{ V}$) $T_A = 25^\circ\text{C}$ $T_A = T_{\text{high}}$ to T_{low} (Note 7)	I_{O+}	20 10	40 20	– –	20 10	40 20	– –	20 10	40 20	– –	20 10	40 20	– –	20 10	40 20	– –	mA
Output Sink Current ($V_{ID} = -1.0\text{ V}$, $V_{CC} = 15\text{ V}$) $T_A = 25^\circ\text{C}$ $T_A = T_{\text{high}}$ to T_{low} (Note 7) ($V_{ID} = -1.0\text{ V}$, $V_O = 200\text{ mV}$, $T_A = 25^\circ\text{C}$)	I_{O-}	10 5.0 12	20 8.0 50	– – –	10 5.0 12	20 8.0 50	– – –	10 5.0 12	20 8.0 50	– – –	10 5.0 –	20 8.0 –	– – –	10 5.0 –	20 8.0 –	– – –	mA μA
Output Short Circuit to Ground (Note 8)	I_{SC}	–	40	60	–	40	60	–	40	60	–	40	60	–	40	60	mA
Power Supply Current ($T_A = T_{\text{high}}$ to T_{low}) (Note 7) $V_{CC} = 30\text{ V}$ $V_O = 0\text{ V}$, $R_L = \infty$ $V_{CC} = 5.0\text{ V}$, $V_O = 0\text{ V}$, $R_L = \infty$	I_{CC}	– –	– –	3.0 1.2	– –	1.4 0.7	3.0 1.2	– –	– –	3.0 1.2	– –	– –	3.0 1.2	– –	– –	3.0 1.2	mA

7. LM224: $T_{\text{low}} = -25^\circ\text{C}$, $T_{\text{high}} = +85^\circ\text{C}$
 LM324/LM324A/LM324E: $T_{\text{low}} = 0^\circ\text{C}$, $T_{\text{high}} = +70^\circ\text{C}$
 LM2902/LM2902E: $T_{\text{low}} = -40^\circ\text{C}$, $T_{\text{high}} = +105^\circ\text{C}$
 LM2902V & NCV2902: $T_{\text{low}} = -40^\circ\text{C}$, $T_{\text{high}} = +125^\circ\text{C}$
 NCV2902 is qualified for automotive use.

8. The input common mode voltage or either input signal voltage should not be allowed to go negative by more than 0.3 V. The upper end of the common mode voltage range is $V_{CC} - 1.7\text{ V}$, but either or both inputs can go to +32 V without damage, independent of the magnitude of V_{CC} .

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

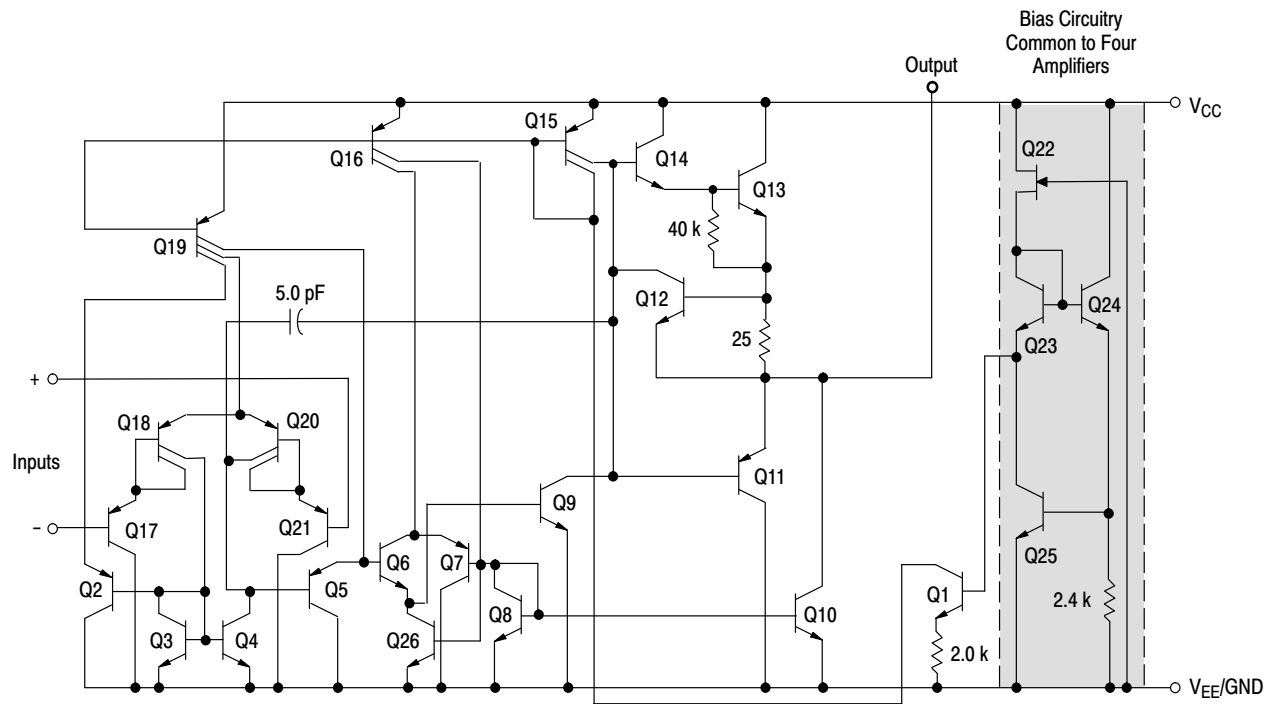


Figure 1. Representative Circuit Diagram
(One-Fourth of Circuit Shown)

CIRCUIT DESCRIPTION

The LM324 series is made using four internally compensated, two-stage operational amplifiers. The first stage of each consists of differential input devices Q20 and Q18 with input buffer transistors Q21 and Q17 and the differential to single ended converter Q3 and Q4. The first stage performs not only the first stage gain function but also performs the level shifting and transconductance reduction functions. By reducing the transconductance, a smaller compensation capacitor (only 5.0 pF) can be employed, thus saving chip area. The transconductance reduction is accomplished by splitting the collectors of Q20 and Q18. Another feature of this input stage is that the input common mode range can include the negative supply or ground, in single supply operation, without saturating either the input devices or the differential to single-ended converter. The second stage consists of a standard current source load amplifier stage.

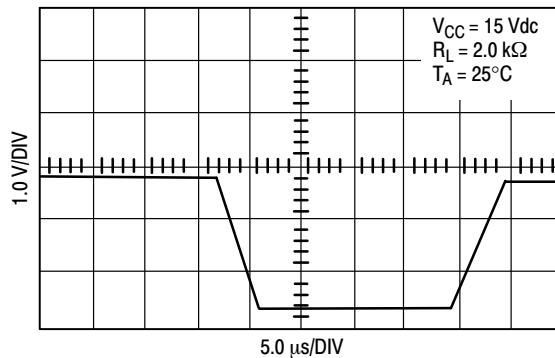


Figure 2. Large Signal Voltage Follower Response

Each amplifier is biased from an internal-voltage regulator which has a low temperature coefficient thus giving each amplifier good temperature characteristics as well as excellent power supply rejection.

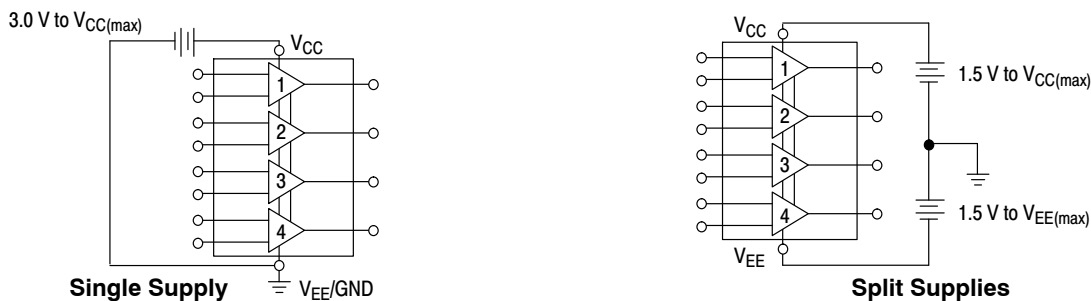


Figure 3.

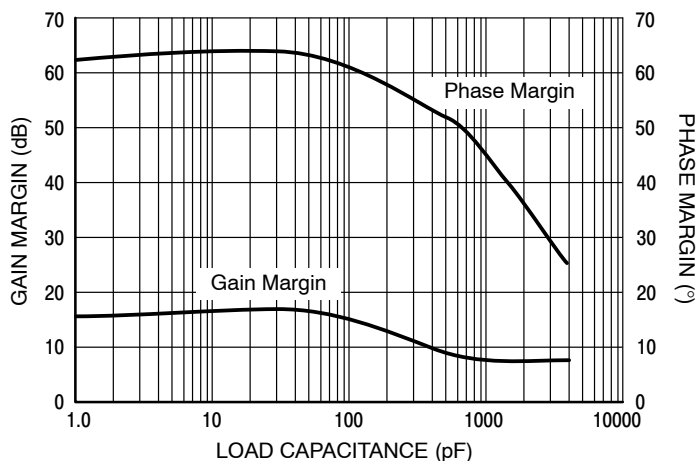


Figure 4. Gain and Phase Margin

LM324, LM324A, LM324E, LM224, LM2902, LM2902E, LM2902V, NCV2902

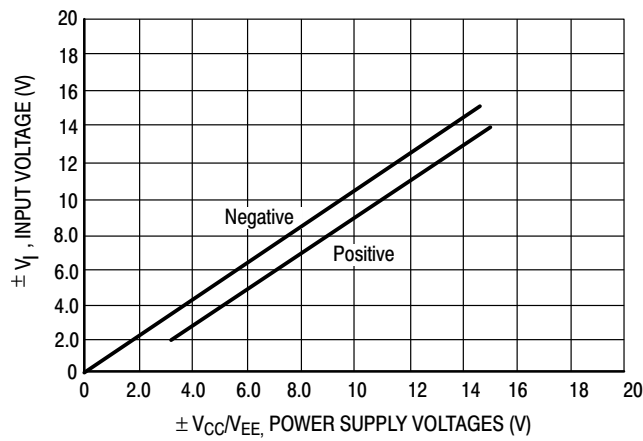


Figure 5. Input Voltage Range

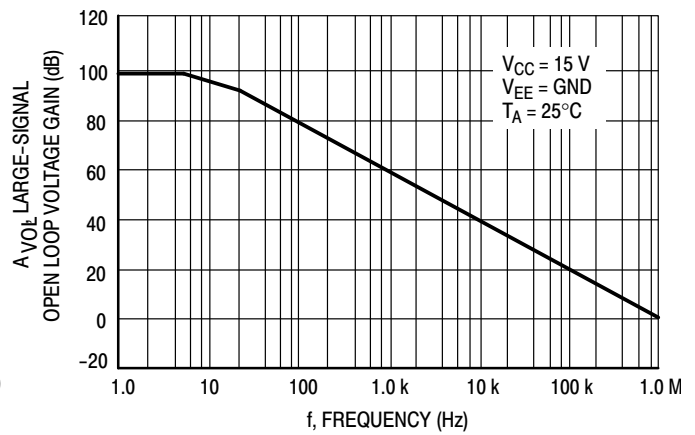


Figure 6. Open Loop Frequency

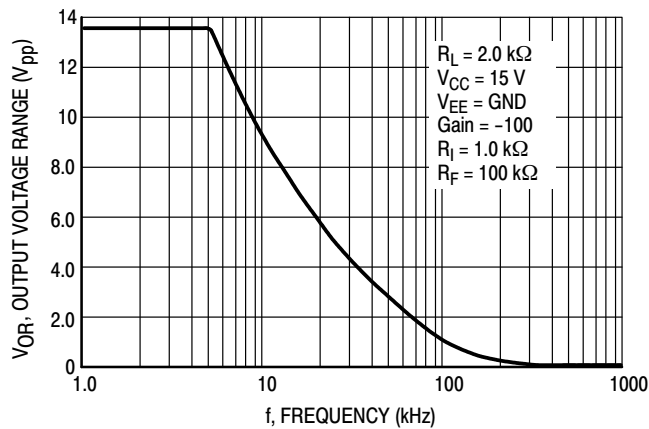


Figure 7. Large-Signal Frequency Response

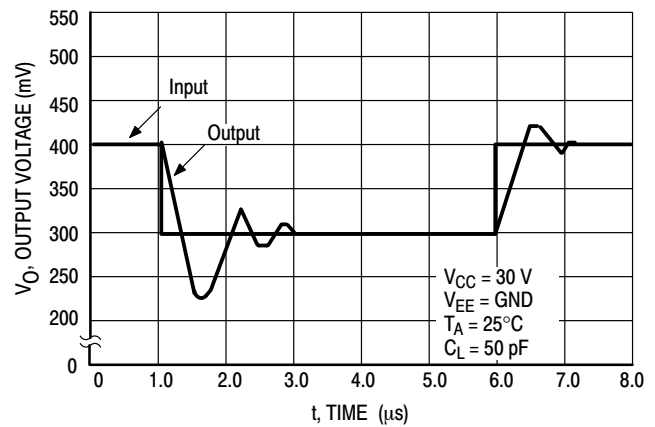


Figure 8. Small-Signal Voltage Follower Pulse Response (Noninverting)

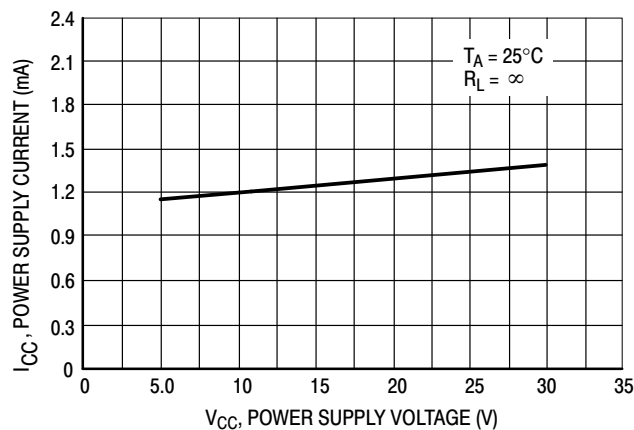


Figure 9. Power Supply Current versus Power Supply Voltage

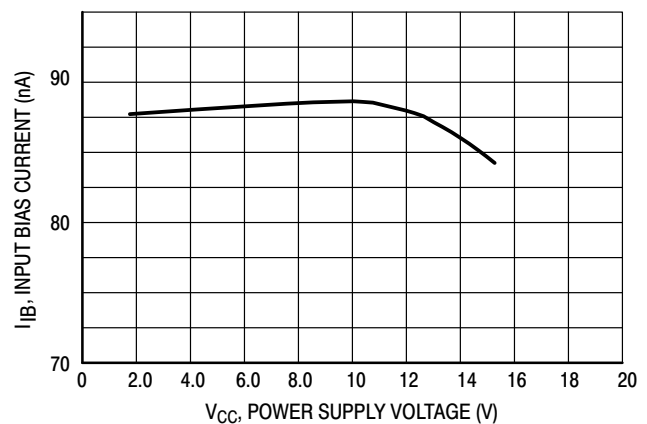


Figure 10. Input Bias Current versus Power Supply Voltage

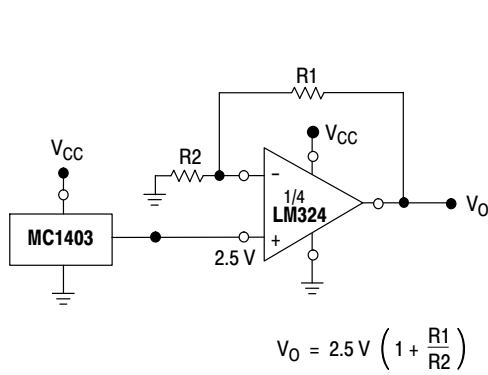


Figure 11. Voltage Reference

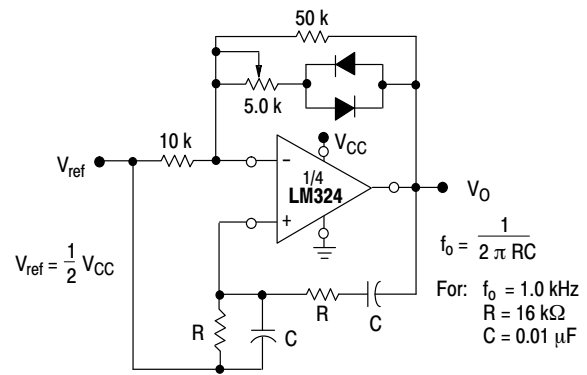


Figure 12. Wien Bridge Oscillator

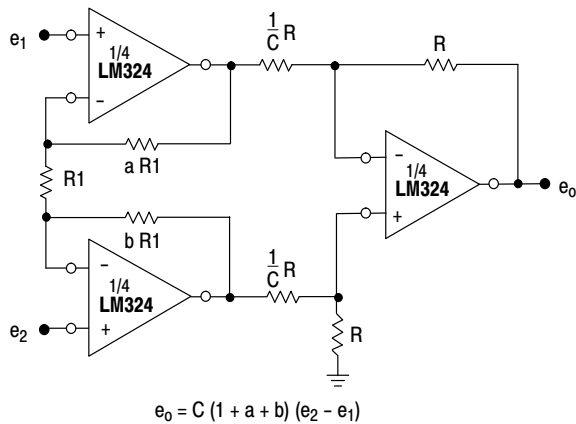


Figure 13. High Impedance Differential Amplifier

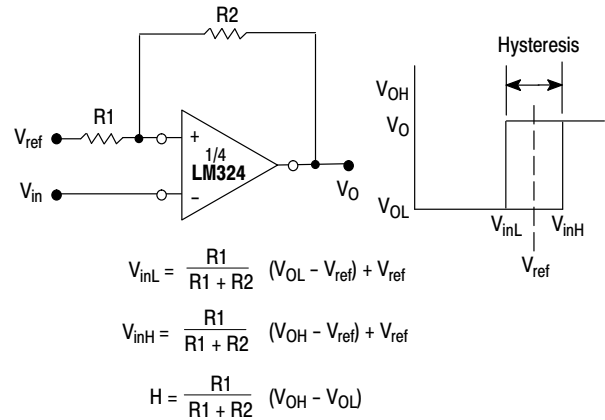


Figure 14. Comparator with Hysteresis

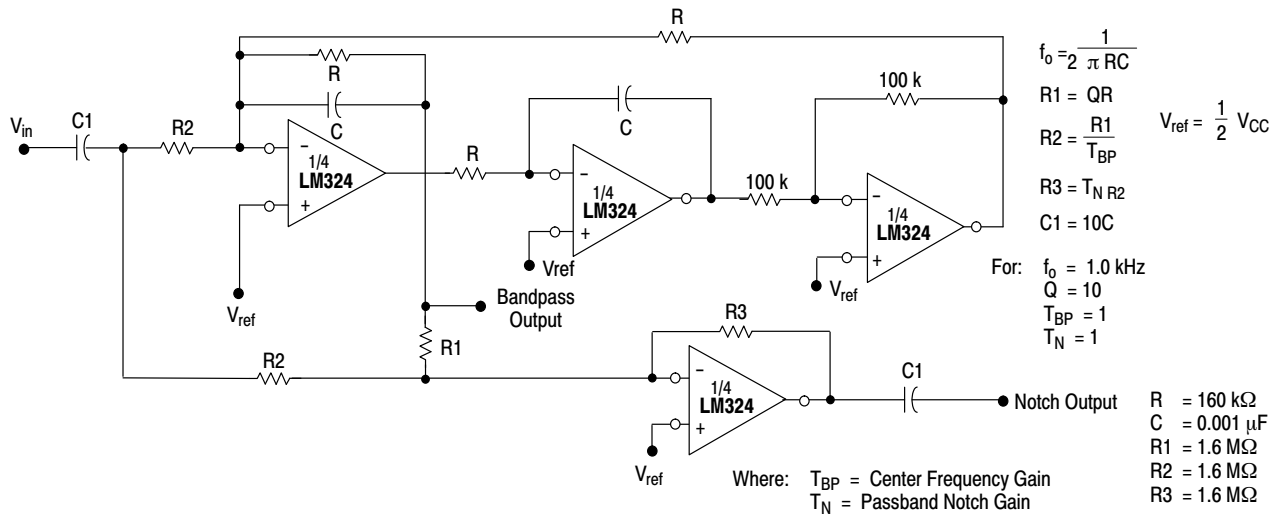


Figure 15. Bi-Quad Filter

LM324, LM324A, LM324E, LM224, LM2902, LM2902E, LM2902V, NCV2902

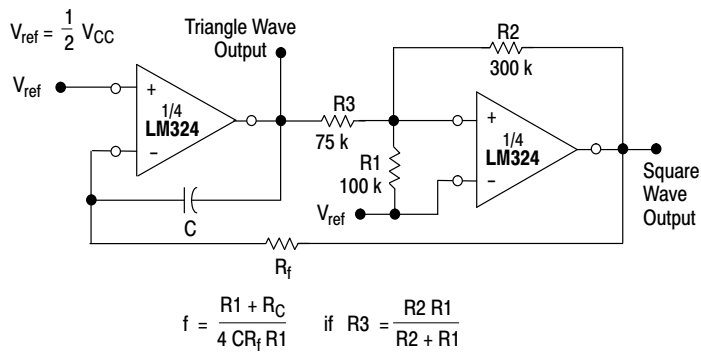


Figure 16. Function Generator

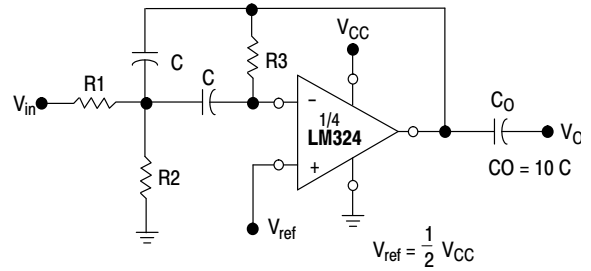


Figure 17. Multiple Feedback Bandpass Filter

Given: f_o = center frequency
 $A(f_o)$ = gain at center frequency

Choose value f_o , C

Then: $R3 = \frac{Q}{\pi f_o C}$

$R1 = \frac{R3}{2 A(f_o)}$

$R2 = \frac{R1 R3}{4 Q^2 R1 - R3}$

For less than 10% error from operational amplifier, $\frac{Q_o f_o}{BW} < 0.1$

where f_o and BW are expressed in Hz.

If source impedance varies, filter may be preceded with voltage follower buffer to stabilize filter parameters.

LM324, LM324A, LM324E, LM224, LM2902, LM2902E, LM2902V, NCV2902

ORDERING INFORMATION

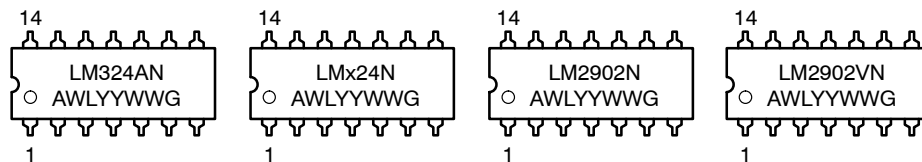
Device	Operating Temperature Range	Package	Shipping [†]
LM224DG	-25°C to +85°C	SOIC-14 (Pb-Free)	55 Units/Rail
LM224DR2G		SOIC-14 (Pb-Free)	2500/Tape & Reel
LM224DTBG		TSSOP-14 (Pb-Free)	96 Units/Tube
LM224DTBR2G		TSSOP-14 (Pb-Free)	2500/Tape & Reel
LM224NG		PDIP-14 (Pb-Free)	25 Units/Rail
LM324DG	0°C to +70°C	SOIC-14 (Pb-Free)	55 Units/Rail
LM324DR2G		SOIC-14 (Pb-Free)	2500/Tape & Reel
LM324EDR2G		SOIC-14 (Pb-Free)	2500/Tape & Reel
LM324DTBG		TSSOP-14 (Pb-Free)	96 Units/Tube
LM324DTBR2G		TSSOP-14 (Pb-Free)	2500/Tape & Reel
LM324NG		PDIP-14 (Pb-Free)	25 Units/Rail
LM324ADG		SOIC-14 (Pb-Free)	55 Units/Rail
LM324ADR2G		SOIC-14 (Pb-Free)	2500/Tape & Reel
LM324ADTBG		TSSOP-14 (Pb-Free)	96 Units/Tube
LM324ADTBR2G		TSSOP-14 (Pb-Free)	2500/Tape & Reel
LM324ANG		PDIP-14 (Pb-Free)	25 Units/Rail
LM2902DG	-40°C to +105°C	SOIC-14 (Pb-Free)	55 Units/Rail
LM2902DR2G		SOIC-14 (Pb-Free)	2500/Tape & Reel
LM2902EDR2G		SOIC-14 (Pb-Free)	2500/Tape & Reel
LM2902DTBG		TSSOP-14 (Pb-Free)	96 Units/Tube
LM2902DTBR2G		TSSOP-14 (Pb-Free)	2500/Tape & Reel
LM2902NG		PDIP-14 (Pb-Free)	25 Units/Rail
LM2902VDG	-40°C to +125°C	SOIC-14 (Pb-Free)	55 Units/Rail
LM2902VDR2G		SOIC-14 (Pb-Free)	2500/Tape & Reel
LM2902VDTBG		TSSOP-14 (Pb-Free)	96 Units/Tube
LM2902VDTBR2G		TSSOP-14 (Pb-Free)	2500/Tape & Reel
LM2902VNG		PDIP-14 (Pb-Free)	25 Units/Rail
NCV2902DR2G*		SOIC-14 (Pb-Free)	2500/Tape & Reel
NCV2902DTBR2G*		TSSOP-14 (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

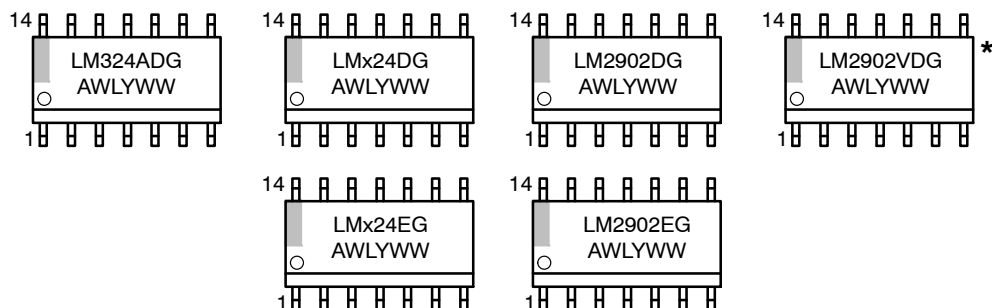
*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MARKING DIAGRAMS

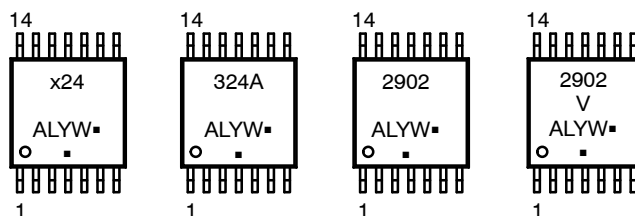
PDIP-14 N SUFFIX CASE 646



SOIC-14 D SUFFIX CASE 751A



TSSOP-14 DTB SUFFIX CASE 948G



x = 2 or 3
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

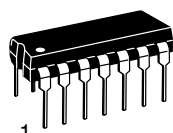
*This marking diagram also applies to NCV2902.

MECHANICAL CASE OUTLINE

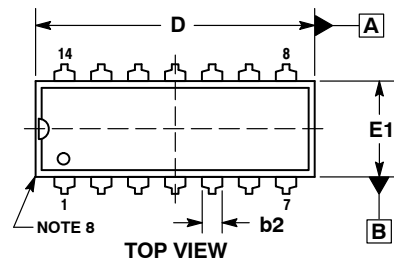
PACKAGE DIMENSIONS

ON Semiconductor®

ON



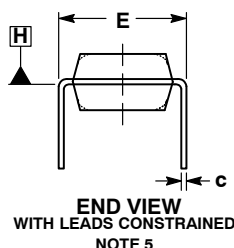
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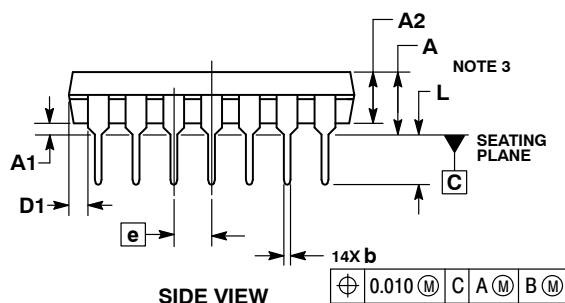
TOP VIEW

PDIP-14
CASE 646-06
ISSUE S

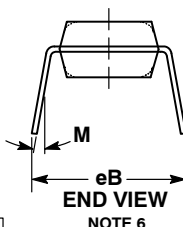
DATE 22 APR 2015



END VIEW
WITH LEADS CONSTRAINED
NOTE 5



SIDE VIEW



END VIEW
NOTE 6

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	----	0.210	----	5.33
A1	0.015	----	0.38	----
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060 TYP		1.52 TYP	
C	0.008	0.014	0.20	0.36
D	0.735	0.775	18.67	19.69
D1	0.005	----	0.13	----
E	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
e	0.100 BSC		2.54 BSC	
eB	----	0.430	----	10.92
L	0.115	0.150	2.92	3.81
M	----	10°	----	10°

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLES ON PAGE 2

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CASE 646-06
ISSUE S

DATE 22 APR 2015

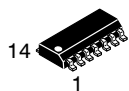
STYLE 1: PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. DRAIN 2. SOURCE 3. GATE 4. NO CONNECTION 5. GATE 6. SOURCE 7. DRAIN 8. DRAIN 9. SOURCE 10. GATE 11. NO CONNECTION 12. GATE 13. SOURCE 14. DRAIN
STYLE 5: PIN 1. GATE 2. DRAIN 3. SOURCE 4. NO CONNECTION 5. SOURCE 6. DRAIN 7. GATE 8. GATE 9. DRAIN 10. SOURCE 11. NO CONNECTION 12. SOURCE 13. DRAIN 14. GATE	STYLE 6: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 7: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE	STYLE 8: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE
STYLE 9: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE	STYLE 10: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 11: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE	STYLE 12: PIN 1. COMMON CATHODE 2. COMMON ANODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. COMMON ANODE 7. COMMON CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. ANODE/CATHODE 14. ANODE/CATHODE

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DESCRIPTION:	PDIP-14	PAGE 2 OF 2

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

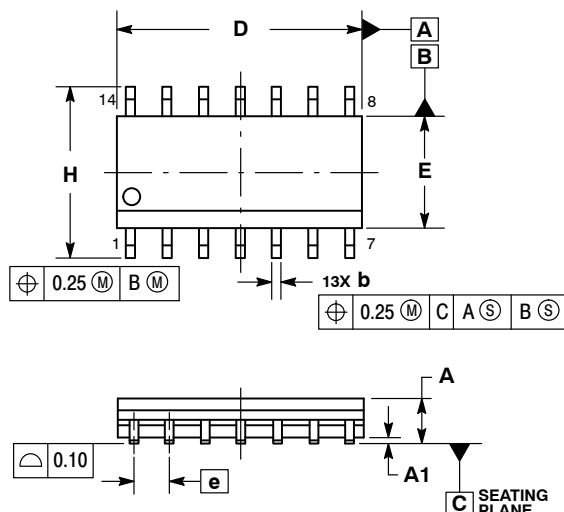
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SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

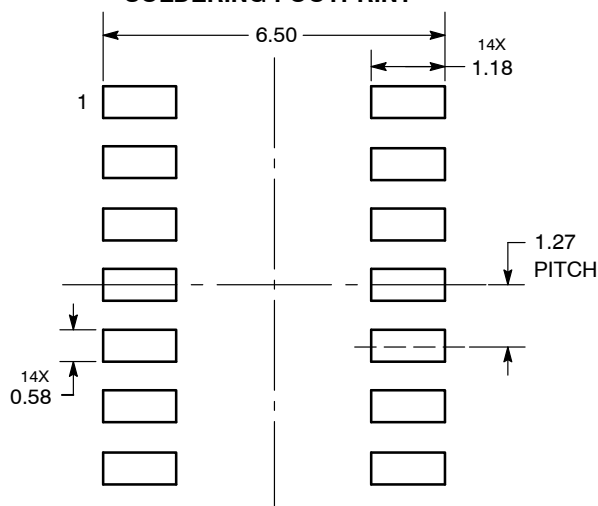


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

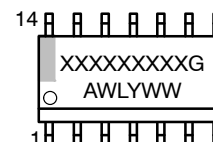
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE


STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

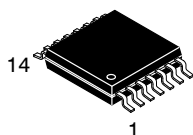
STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

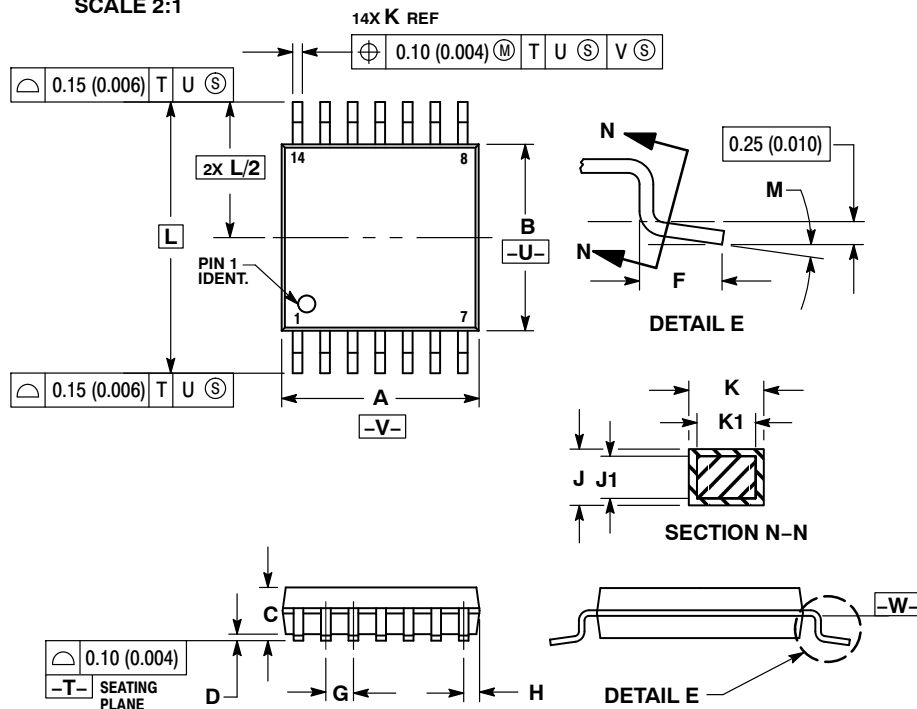
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SCALE 2:1

TSSOP-14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016

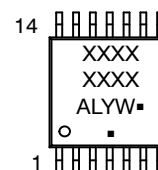


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

GENERIC MARKING DIAGRAM*

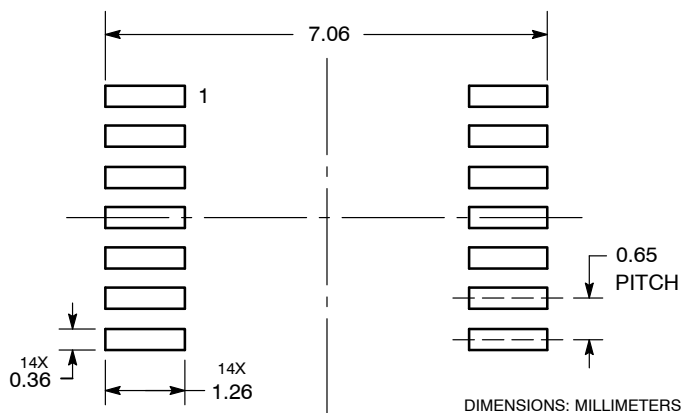


A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT



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DESCRIPTION: TSSOP-14 WB

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